

PS7214-1A

4-PIN SOP, 1.0 Ω LOW ON-STATE RESISTANCE 1-ch Optical Coupled MOS FET

DESCRIPTION

The PS7214-1A is a low on-state resistance solid state relay containing a GaAs LED on the input side and MOS FETs on the output side.

It is suitable for PLC, etc. because of its large continuous load current and low on-state resistance.

FEATURES

- Low on-state resistance ($R_{on} = 1.0 \Omega \text{ TYP.}$)
- Large continuous load current (I_L = 400 mA)
- 1 channel type (1 a output)
- · Designed for AC/DC switching line changer
- Small and thin package (4-pin SOP, Height = 2.1 mm)
- High isolation voltage (BV = 1 500 Vr.m.s.)
- Low offset voltage
- Ordering number of taping product : PS7214-1A-E3, E4: 900 pcs/reel

: PS7214-1A-F3, F4: 3 500 pcs/reel

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· Pb-Free product

Safety standards

• UL approved: File No. E72422

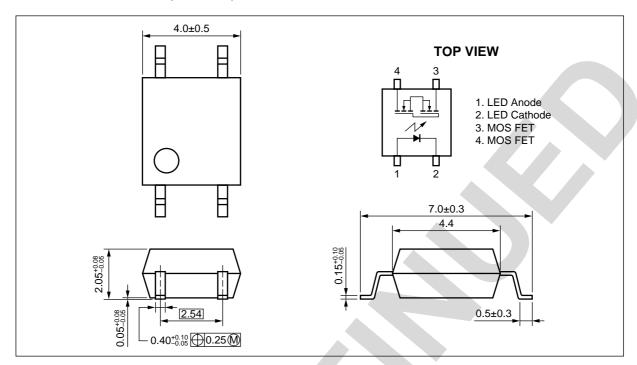
• BSI approved: No. 8241/8242

APPLICATIONS

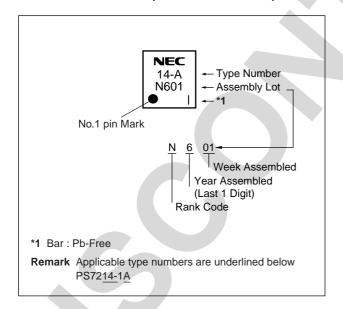
- · Measurement equipment
- · FA equipment

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PACKAGE DIMENSIONS (Unit: mm)



<R> MARKING EXAMPLE (LASER MARKING)



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number*1
PS7214-1A	PS7214-1A-A	Pb-Free	Magazine case 100 pcs	Standard products	PS7214-1A
PS7214-1A-E3	PS7214-1A-E3-A		Embossed Tape 900 pcs/reel	(UL, BSI	
PS7214-1A-E4	PS7214-1A-E4-A			approved)	
PS7214-1A-F3	PS7214-1A-F3-A		Embossed Tape 3 500 pcs/reel		
PS7214-1A-F4	PS7214-1A-F4-A				

^{*1} For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lF	50	mA
	Reverse Voltage	VR	5.0	V
	Power Dissipation	Po	50	mW
	Peak Forward Current*1	IFP	1	А
MOS FET	MOS FET Break Down Voltage		100	V
	Continuous Load Current	lι	400	mA
	Pulse Load Current*2 (AC/DC Connection)	ILP	0.8	А
	Power Dissipation	Po	300	mW
Isolation Voltage*3		BV	1 500	Vr.m.s.
Total Power Dissipation		Рт	350	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

^{*1} PW = 100 μ s, Duty Cycle = 1%

^{*2} PW = 100 ms, 1 shot

^{*3} AC voltage for 1 minute at $T_A = 25$ °C, RH = 60% between input and output Pins 1-2 shorted together, 3-4 shorted together.

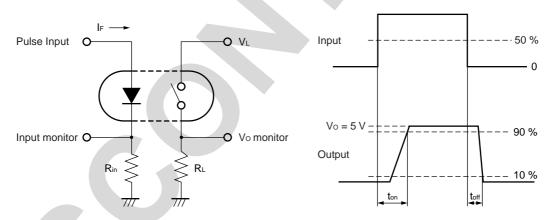
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lF	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

ELECTRICAL CHARACTERISTICS (TA = 25°C)

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode Forward Voltage		VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	lR	V _R = 5 V			5.0	μА
MOS FET	Off-state Leakage Current	Loff	V _D = 100 V			1.0	μА
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		120		pF
Coupled	LED On-state Current	IFon	IL = 400 mA			2.0	mA
	On-state Resistance	Ron	$I_F = 10 \text{ mA}, I_L = 400 \text{ mA}, t \le 10 \text{ ms}$		1.0	1.2	Ω
	Turn-on Time *1, 2	ton	If = 10 mA, Vo = 5 V, RL = 500 Ω ,		1.3	2.0	ms
	Turn-off Time *1, 2	t off	PW ≥ 10 ms		0.1	1.0	
	Isolation Resistance	R _{I-O}	Vi-o = 1.0 kVpc	10 ⁹			Ω
	Isolation Capacitance	Cı-o	V = 0 V, f = 1 MHz		0.5		pF

*1 Test Circuit for Switching Time

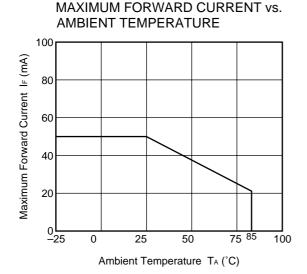


*2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms.

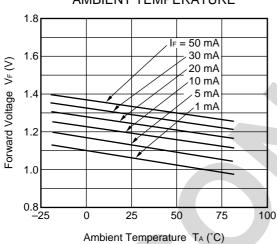
Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

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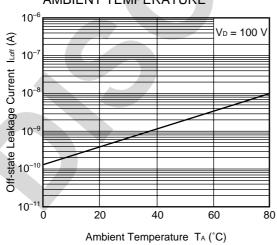
TYPICAL CHARACTERISTICS (Ta = 25°C, unless otherwise specified)



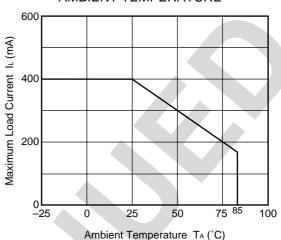




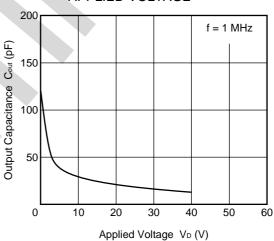
OFF-STATE LEAKAGE CURRENT vs. AMBIENT TEMPERATURE



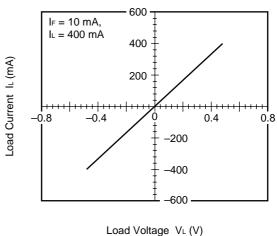
MAXIMUM LOAD CURRENT vs. AMBIENT TEMPERATURE



OUTPUT CAPACITANCE vs. APPLIED VOLTAGE

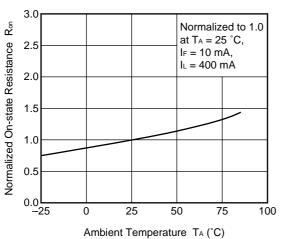


LOAD CURRENT vs. LOAD VOLTAGE

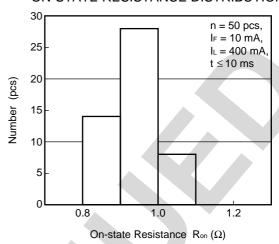


Remark The graphs indicate nominal characteristics.

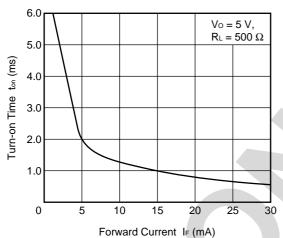
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



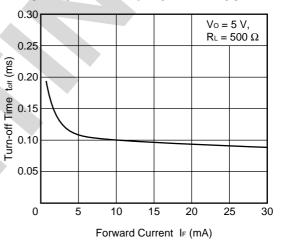
ON-STATE RESISTANCE DISTRIBUTION



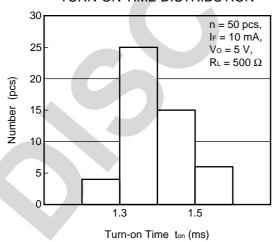
TURN-ON TIME vs. FORWARD CURRENT



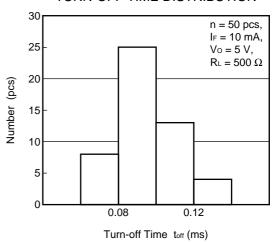
TURN-OFF TIME vs. FORWARD CURRENT



TURN-ON TIME DISTRIBUTION

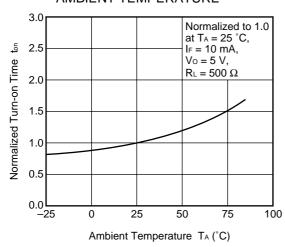


TURN-OFF TIME DISTRIBUTION



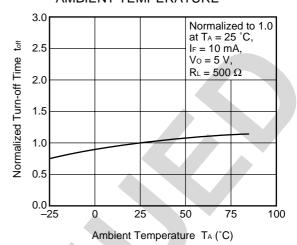
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-ON TIME vs. AMBIENT TEMPERATURE

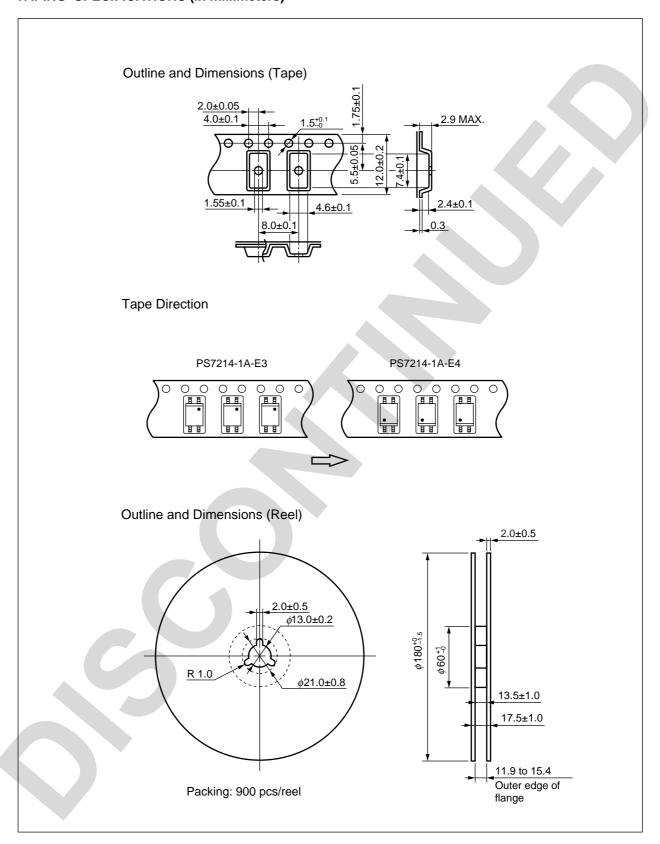


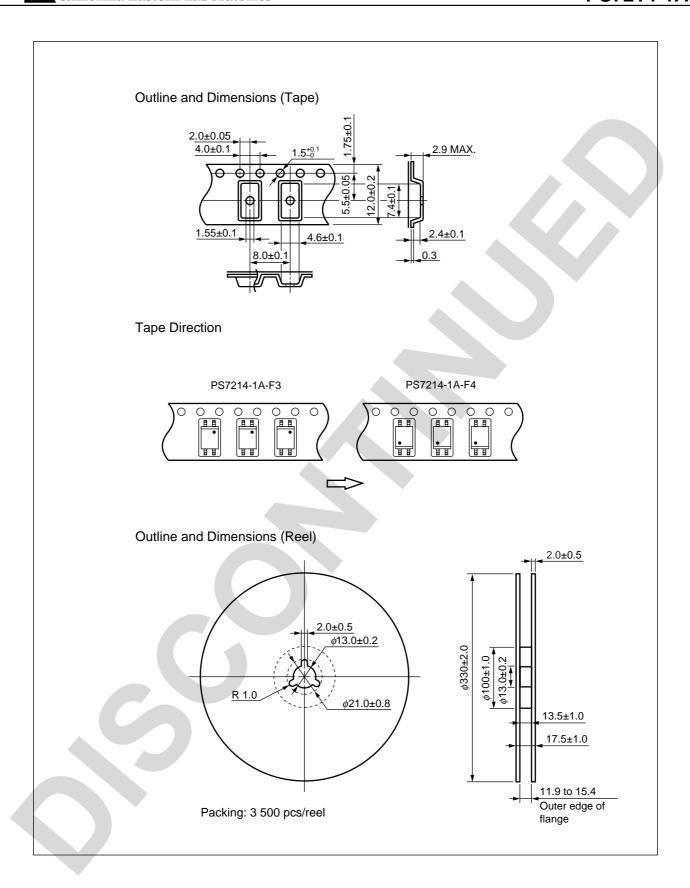
Remark The graphs indicate nominal characteristics.

NORMALIZED TURN-OFF TIME vs. AMBIENT TEMPERATURE



TAPING SPECIFICATIONS (in millimeters)





RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

Peak reflow temperature
 260°C or below (package surface temperature)

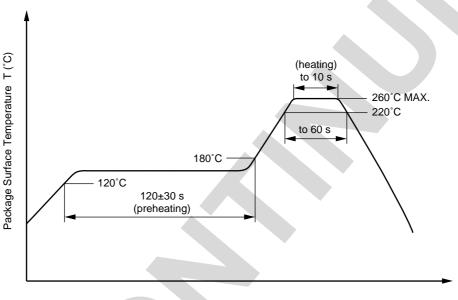
Time of peak reflow temperature
 Time of temperature higher than 220°C
 10 seconds or less
 60 seconds or less

Time to preheat temperature from 120 to 180°C 120±30 s
 Number of reflows Three

Flux
 Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

• Temperature 260°C or below (molten solder temperature)

• Time 10 seconds or less

Preheating conditions
 120°C or below (package surface temperature)

• Number of times One

Flux
 Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

content of 0.2 Wt% is recommended.)

<R> (3) Soldering by soldering iron

Peak temperature (lead part temperature)
 Time (each pins)
 350°C or below
 3 seconds or less

Rosin flux containing small amount of chlorine (The flux with a

maximum chlorine content of 0.2 Wt% is recommended.)

- (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.
- (b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- 1. Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.



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M8E 02.11-1

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
 - Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.

▶ For further information, please contact

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